GX74470, Package Outline Drawing

9.1 x 14.0 x 2.32 mm Module

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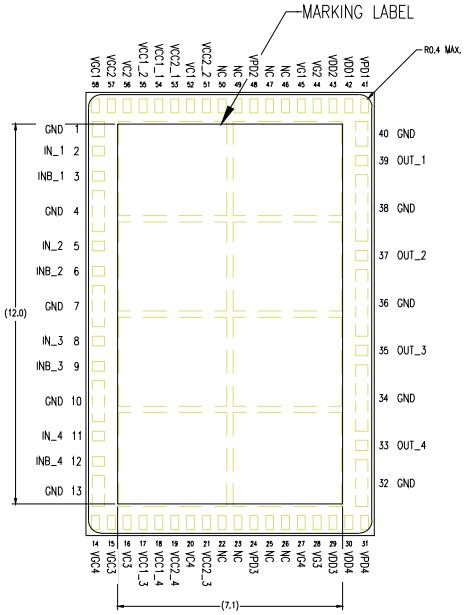
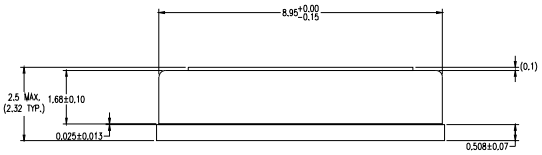
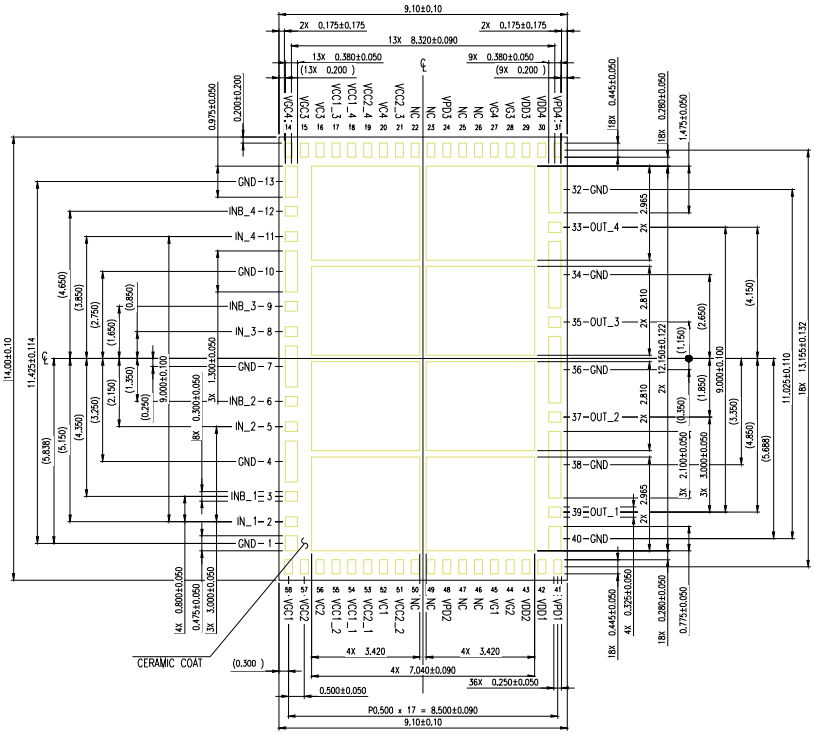


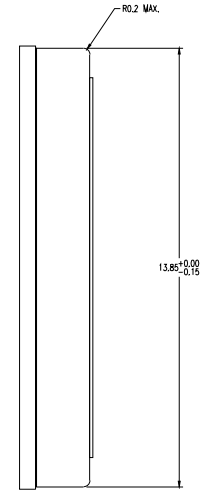
TOP VIEW



SIDE VIEW – DC INPUTS



BOTTOM VIEW



SIDE VIEW – RF OUTPUTS

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS (mm).
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M 1994.
3. TOTAL THICKNESS DOES NOT INCLUDE SAW BURR.
4. CONNECT UNLABELED (LARGE) PADS TO GROUND.

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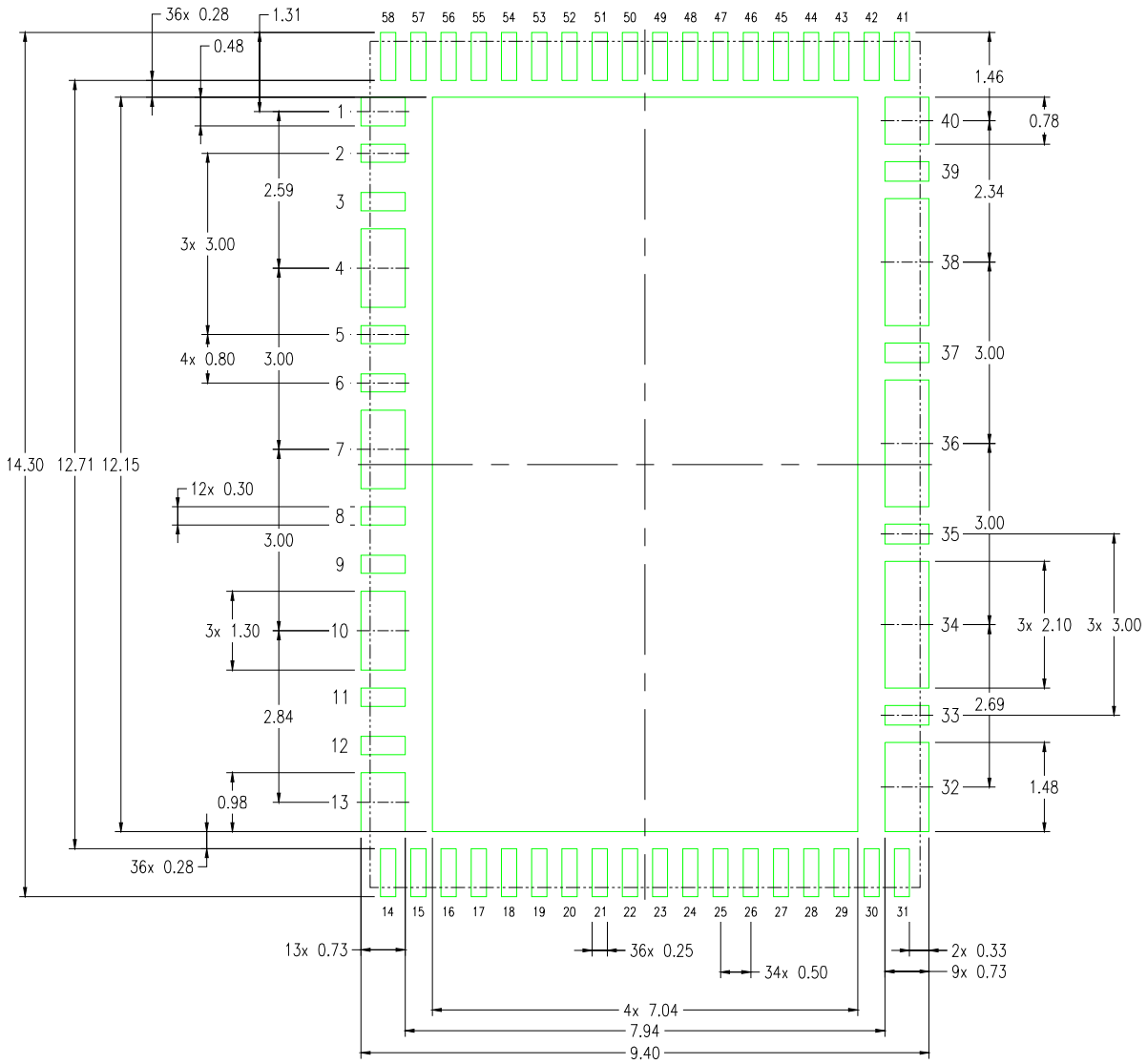

RECOMMENDED LAND PATTERN DIMENSION

NOTES:

1. ALL DIMENSION ARE IN MILLIMETERS. ANGLES IN DEGREES.
2. TOP DOWN VIEW. AS VIEWED ON PCB.
3. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

Package Revision History		
Date Created	Rev No.	Description
July 12, 2019	Rev 00	Initial Release
June 21, 2021	Rev 01	Update to Renesas Logo

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